

**AMENDMENT TO THE CLAIMS:**

This listing of the claims will replace all prior versions, and listings, of claims in the application.

**LISTING OF CLAIMS:**

Claim 1. (Currently Amended) A method for fabricating W-Cu alloy having a homogenous micro-structure ~~micro-homogeneous structure~~, comprising:

forming mixed powders by mixing tungsten powders with W-Cu composite powders;  
forming a compact by pressurizing-forming the mixed powders;  
forming a skeleton by sintering the compact; and  
contacting copper to the skeleton and performing infiltration.

Claim 2. (Currently Amended) The method of claim 1, wherein the W-Cu composite powders are obtained by (a) mixing together a powder comprised of a mixture of WO<sub>3</sub> and WO<sub>2</sub> with a copper oxide powder comprised of a mixture of CuO and Cu<sub>2</sub>O; (b) milling the product of step (a) and (c) performing reduction heat treatment on the product of (b) to form said W-Cu-composite powder in which the tungsten powder covers the copper powder. ~~a method disclosed in Korean Patent No. 24857, wherein homogeneous globular-shaped powders in which a tungsten powder covers a copper powder are obtained by mixing tungsten oxide (WO<sub>3</sub> and WO<sub>2.5</sub>) powders with copper oxide (CuO and Cu<sub>2</sub>O) powders, milling the mixture and performing reduction heat treatment.~~

Claim 3. (Original) The method of claim 1, wherein the mixture of tungsten powders and W-Cu composite powders has a tungsten:copper ratio by weight as 20:1 or 2:1.

Claim 4. (Original) The method of claim 1, wherein sintering of the compact is performed at a

temperature not less than 1083 °C as a melting temperature of copper in a reduction gas atmosphere including hydrogen.

Claim 5. (Original) The method of claim 1, wherein infiltration of copper is performed at a temperature not less than 1083 °C as a melting temperature of copper in a reduction gas atmosphere including hydrogen.

Claim 6. (Currently Amended) The method according to one of claims 1~5, wherein the W-Cu alloy having a homogeneous micro-structure is fabricated by a method according to ~~one of~~ claims 1~5.

Claims 7-8. (Cancelled)